Part Description:	AS4C64M16MD1-6BCN / AS4C64M16MD1-6BIN
Wieght (mg):	157.697 mg

No.	Part Name	Material Name	Material mass (mg)	Substance in Materials	CAS Number	Element wt (%)	Element wt (mg)	wt % of total unit wt	PPM
1	Substrate	BT HL832	32.381	Core-HL-832	Trade secret	57.584%	18.646	11.823%	575840
				Solder Mask-AUS308	Trade secret	12.702%	4.113	2.607%	127020
				Cu	7440-50-8	28.658%	9.280	5.884%	286580
				Ni	7440-02-0	0.933%	0.302	0.191%	9330
				Au	7440-57-5	0.123%	0.040	0.025%	1230
2	Compound	G750	81.373	Epoxy,Cresol Novolac	29690-82-2	9.99781%	8.136	5.16%	99978.14
				Phenol Novolac	9003-35-4	5.00831%	4.075	2.58%	50083.13
				Metal Hydroxide	Trade secret	7.50263%	6.105	3.87%	75026.31
				Carbon black	1333-86-4	0.30465%	0.248	0.16%	3046.46
				Silica fused	60676-86-0	73.87312%	60.113	38.13%	738731.24
				Silica fused	7631-86-9	3.00835%	2.448	1.55%	30083.46
				Silica, crystalline	14808-60-7	0.30465%	0.248	0.16%	3046.46
3	Die Adhesive	ADHESIVE 6200	1.815	Rubber modified epoxy	Trade secret	44.899%	0.815	0.52%	448986.6126
				Diethylene glycol monoethyl ether acetate	112-15-2	34.697%	0.630	0.40%	346974.7195
				Carbamate resin	Trade secret	10.200%	0.185	0.12%	102003.2853
				Maleimide resin	Trade secret	5.102%	0.093	0.06%	51018.85837
				Bismaleimide resin	Trade secret	5.102%	0.093	0.06%	51018.85837
4	Solder Ball	M705	21.185	Sn	7440-31-5	96.5001%	20.444	12.96%	965001.2273
				Ag	7440-22-4	3.0000%	0.636	0.40%	30000.1539
				Cu	7440-50-8	0.5000%	0.106	0.07%	5000.02565
5	Gold Wire	Au	0.317	Gold	7440-57-5	100.0000%	0.317	0.20%	1000000
6	Chip	Silicon	20.626	Silica	7440-21-3	100.00%	20.626	13.08%	1000000

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